



### SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

## **REVERSE VOLTAGE - 40 Volts** FORWARD CURRENT - 1.0 Ampere

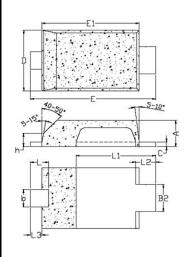
#### **FEATURES**

- Very low profile package 0.80mm
- Super fast switching for high efficiency
- For surface mounted applications
- · Very Low forward voltage drop and high current capability
- · Low reverse leakage current

#### **MECHANICAL DATA**

- Case: JEDEC DO-222AA
- Case Material: Molding compound, UL Flammability classification 94V-0, (No Br. Sb. Cl.) "Halogen-free"
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Lead Free Plating (Matte Tin Finish.)
- Component in accordance to RoHs 2002/95/EC

# **Mite Flat**



Mite Flat						
DIM.	MIN. MAX.					
A	0.80	0.95				
b		0.00				
	0.40	0.65				
b2	0.70	1.00				
С	0.10	0.25				
D	1.75	2.05				
Е	3.60	3.90				
E1	2.80	3.10				
h	0.35	0.50				
L	0.50	0.80				
L1	2.10	2.60				
L2	0.45	0.75				
L3	0.20	0.50				
All dimension in millimeter						

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

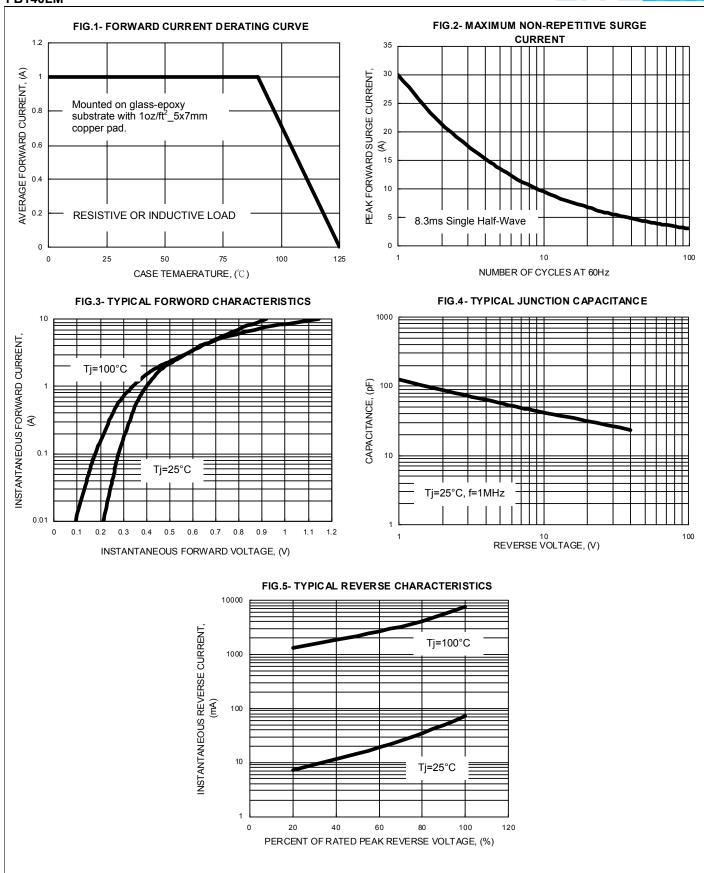
PARAMETER			SYMBOL	FB140LM		UNIT
Device marking code			Note	B1G		
Maximum Repetitive Peak Reverse Voltage			$V_{RRM}$	40		V
Maximum DC Blocking Voltage			V <sub>DC</sub>		40	
Average Rectified Output Current @T <sub>C</sub> =90°C		I <sub>(AV)</sub>	1.0		Α	
Peak Forward Surge Current 8.3ms single half sine-wave			I <sub>FSM</sub>		30	Α
Forward Voltage (1)	=1.0A	@Tj=25°C	V <sub>F</sub>		0.45	
Leakage Current (1) VI	DC=Rated	@Tj=25°C @Tj=100°C	I <sub>R</sub>		1 15	mA
Typical junction capacitance (2)			CJ		65	
Operating junction temperature			TJ	-55 to +125		°C
Storage temperature range			T <sub>STG</sub>	-55 to +150		°C
THERMAL CHARACTERISTIC			SYMBOL	Ту	/pical	UNIT
			R⊕ <sub>JC</sub>		22	
Typical thermal resistance (3, 4)		R⊖JL		48	°C/W	
			R⊖ <sub>Ja</sub>			
Note:					REV. 1 , Aug-2014, KSHP16	

(1) 300us Pulse width, 2% Duty cycle.

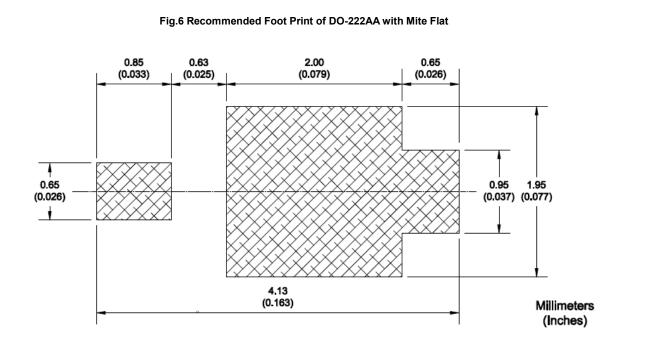
Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

(3) Thermal Resistance test performed in accordance with JESD-51. Unit mounted on glass-epoxy substrate with 1oz/ft2\_7x5 mm copper pad.
(4) Thermal resistance to Case, Lead and Ambient.











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